

Title (en)

Apparatus for electronic assembly with improved interconnect and associated methods

Title (de)

Vorrichtung für eine elektronische Baugruppe mit verbesserter Verbindung und zugehörige Verfahren

Title (fr)

Appareil pour ensemble électronique avec interconnexion améliorée et procédés associés

Publication

**EP 2779226 A1 20140917 (EN)**

Application

**EP 14158359 A 20140307**

Priority

US 201313802687 A 20130313

Abstract (en)

An apparatus includes a substrate that includes electronic circuitry. The apparatus further includes a first die that includes electronic circuitry, and at least one shielded interconnect. The shielded interconnect(s) couple(s) electronic circuitry in the substrate to electronic circuitry in the first die.

IPC 8 full level

**H01L 23/13** (2006.01); **H01L 23/498** (2006.01); **H01L 23/552** (2006.01)

CPC (source: EP US)

**H01L 23/13** (2013.01 - EP US); **H01L 23/3135** (2013.01 - EP US); **H01L 23/49827** (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 24/73** (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 24/16** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 25/0652** (2013.01 - EP US); **H01L 2224/131** (2013.01 - EP US); **H01L 2224/16225** (2013.01 - EP US); **H01L 2224/45012** (2013.01 - EP US); **H01L 2224/45015** (2013.01 - EP US); **H01L 2224/45016** (2013.01 - EP US); **H01L 2224/451** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - EP US); **H01L 2224/45572** (2013.01 - EP US); **H01L 2224/45624** (2013.01 - EP US); **H01L 2224/45647** (2013.01 - EP US); **H01L 2224/45686** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48145** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/4903** (2013.01 - EP US); **H01L 2224/73257** (2013.01 - EP US); **H01L 2224/8592** (2013.01 - EP US); **H01L 2225/0651** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06537** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/15159** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19107** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

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DOCDB simple family (application)

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